Assembly Notes:
1. Built on PMP11368 Rev A PCB.
2. C100 and U100 were added for Rev B.
3. C11 and L3 do not match PCB land pattern.

- C110 and L3 do not match PCB land pattern.
- C100 and U100 were added for Rev B.
- Built on PMP11368 Rev A PCB.

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